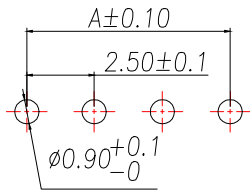
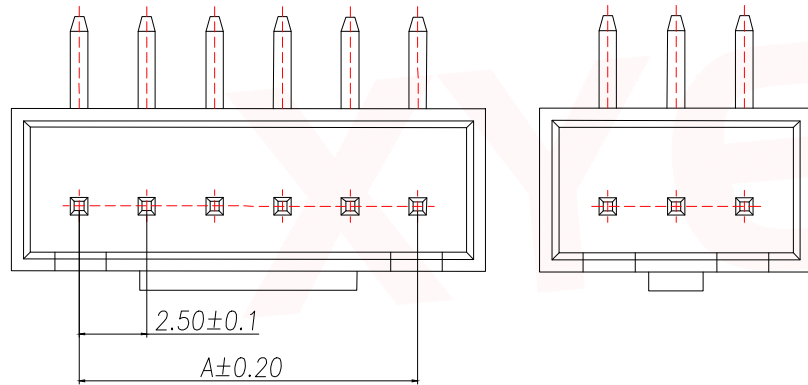
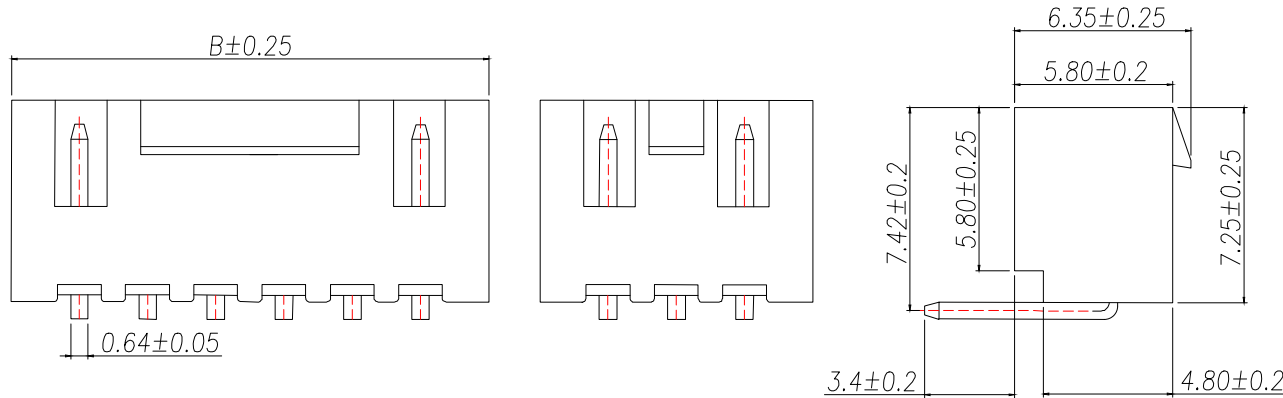


REV.	Q'TY	ECN. NO.	APR.	DATE



SUGGESTED PCB LAYOUT  
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66(UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻:  $\leq 10m\Omega$
4. 绝缘电阻:  $\geq 100M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度:  $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积  $\geq 95\%$  温度 235 , 时间  $2.5\pm 0.5$  秒
10. 铅和铜等六大有害物质含量要符合环保要求.

Part No	Pin	A	B
XY-XHB2.54-2A21	2	2.50	7.50
XY-XHB2.54-3A21	3	5.00	10.00
XY-XHB2.54-4A21	4	7.50	12.50
XY-XHB2.54-5A21	5	10.00	15.00
XY-XHB2.54-6A21	6	12.50	17.50
XY-XHB2.54-7A21	7	15.00	20.00
XY-XHB2.54-8A21	8	17.50	22.50
XY-XHB2.54-9A21	9	20.00	25.00
XY-XHB2.54-10A21	10	22.50	27.50
XY-XHB2.54-11A21	11	25.00	30.00
XY-XHB2.54-12A21	12	27.50	32.50
XY-XHB2.54-13A21	13	30.00	35.00
XY-XHB2.54-14A21	14	32.50	37.50
XY-XHB2.54-15A21	15	35.00	40.00
XY-XHB2.54-16A21	16	37.50	42.50
XY-XHB2.54-17A21	17	40.00	45.00
XY-XHB2.54-18A21	18	42.50	47.50
XY-XHB2.54-19A21	19	45.00	50.00
XY-XHB2.54-20A21	20	47.50	52.50

2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍30u"MIN, 再镀锡80u"MIN
1	基座Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注

DIMENSION IN mm		<p>厦门市辛译精密电子有限公司</p> <p>Xiamen XinYi Xyconn Electronics Co.,Ltd</p>			
TOLERANCE UNLESS OTHERWISE SPECIFIED					
.X±0.35	X.*± 5°	APR.	Alex	TITLE: WAFER XHB2.54MM 带扣 弯针	
.XX±0.25	.X*± 3°	CHK.	Jack	DWG NO. XY-XHB2.54-NA21	
.XXX±0.15	.XX*± 1°	DRA.	Can	PROJ.  CUSTOMER DRAWING SIZE A4 SCALE 1:1 SHEET 1/1 REV. A	